

Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode

These devices are well suited for high efficiency fast switching applications.

Features

- ◆ -20V/-4.1A, $R_{DS(ON)} = 65m\Omega @ V_{GS} = -4.5V$
- ◆ Improved dv/dt capability
- ◆ Suit for -1.8V Gate Drive Applications
- ◆ Fast switching
- ◆ SOT-23 package design

Applications

- ◆ Notebook
- ◆ Battery Protection
- ◆ Load Switch
- ◆ Hand-held Instruments

Pin Configuration



Absolute Maximum Ratings (T_C=25°C Unless Otherwise Noted)

Parameter		Symbol	Maximum	Unit
Drain-Source Voltage		V _{DS}	-20	V
Gate- Source Voltage		V _{GS}	± 10	V
Continuous Drain Current	T _C = 25 °C	I _D	-4.1	A
	T _C = 100 °C		-2.6	
Pulsed Drain Current		I _{DM}	-16.4	A
Power Dissipation	T _C = 25 °C	P _D	1.56	W
	Derate above 25 °C		0.012	
Operating junction temperature range		T _J	- 55 to 150	°C
Storage temperature range		T _{STG}	- 55 to 150	°C

Thermal Resistance Ratings

Parameter	Symbol	Maximum	Unit
Junction-to-Ambient	R _{θJA}	80	°C/W



Ordering Information

Device	Package	Remark
ECDN2313S	SOT-23	3000 pcs / Reel

Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Parameters						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-20	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D = -250μA	-0.4	-0.6	-0.8	V
Gate Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±10 V	-	-	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -20V, V _{GS} = 0V T _J = 25 °C	-	-	-1	μA
		V _{DS} = -16V, V _{GS} = 0V, T _J = 125 °C	-	-	-10	
Forward Trans conductance ^A	g _{fs}	V _{DS} = -10V, I _D = -3A	-	5.5	-	S
Drain-Source On-State Resistance ^A	R _{DS(ON)}	V _{GS} = -4.5V, I _D = -3A	-	52	65	mΩ
		V _{GS} = -2.5V, I _D = -2A	-	73	85	
		V _{GS} = -1.8V, I _D = -1.5A	-	105	130	
Dynamic Parameters						
Input Cap.	C _{iss}	V _{DS} = -10V, V _{GS} = 0V, F = 1MHz	-	515	745	pF
Output Cap.	C _{oss}		-	55	80	
Reverse Transfer Cap.	C _{riss}		-	20	30	
Total Gate Charge ^B	Q _g	V _{DS} = -10V, V _{GS} = -4.5V, I _D = -3A	-	6.4	9	nC
Gate-Source Charge ^B	Q _{gs}		-	0.9	1	
Gate-Drain Charge ^B	Q _{gd}		-	1.6	3	
Turn-On Time ^B	t _{d(ON)}	V _{DD} = -10V, I _D = -1A, V _{GS} = -4.5V, R _G = 25Ω	-	5	9	nS
	t _r		-	17.4	33	
Turn-Off Time ^B	T _{d(OFF)}		-	40.7	80	
	T _f		-	11.4	23	
Source-Drain Diode Ratings And Characteristics						
Continuous Current	I _S	V _G = V _D = 0V, Force Current	-	-	-4.1	A
Pulsed Current ^C	I _{SM}		-	-	-16.4	A
Diode Forward Voltage ^A	V _{SD}	I _S = -1A, V _{GS} = 0V	-	-	-1	V

Note

A: Pulse test: Pulse width ≤ 300μsec, Duty Cycle ≤ 2%

B: Independent of operating temperature

C: Pulse width limited by maximum junction temperature.

Typical Characteristics

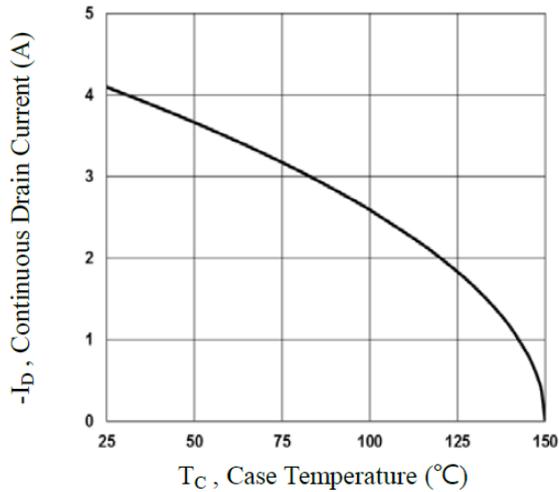


Fig.1 Continuous Drain Current vs. T_c

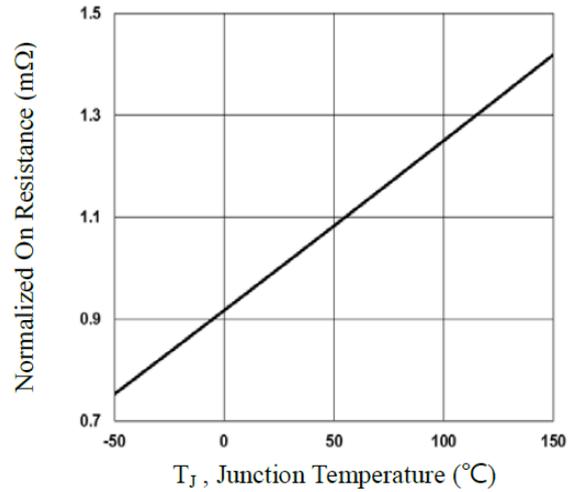


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

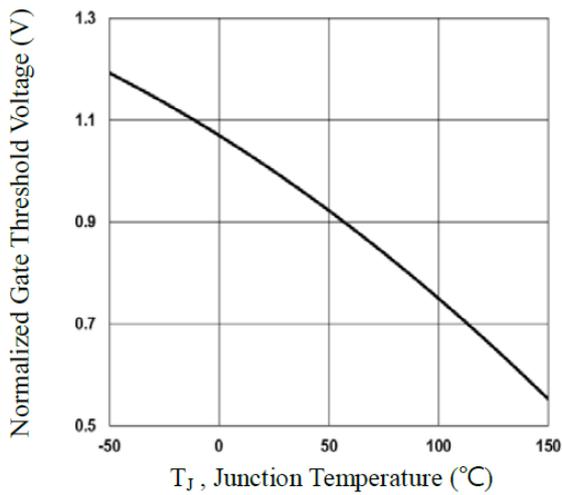


Fig.3 Normalized V_{th} vs. T_j

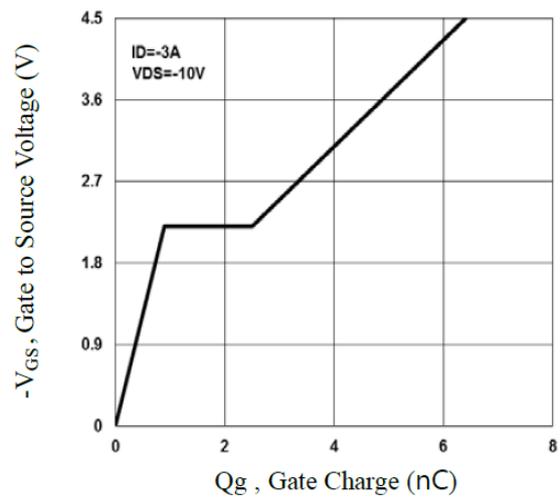


Fig.4 Gate Charge Waveform

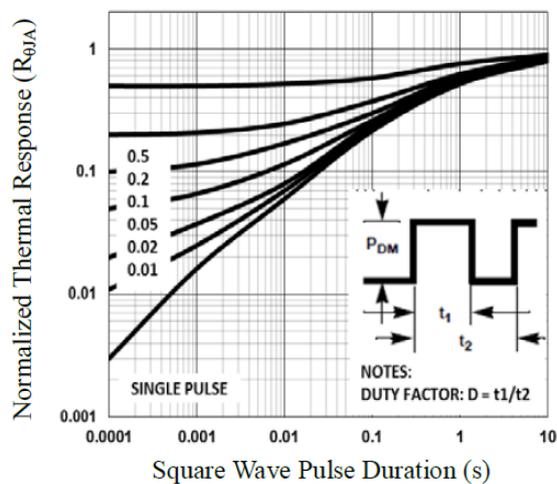


Fig.5 Normalized Transient Impedance

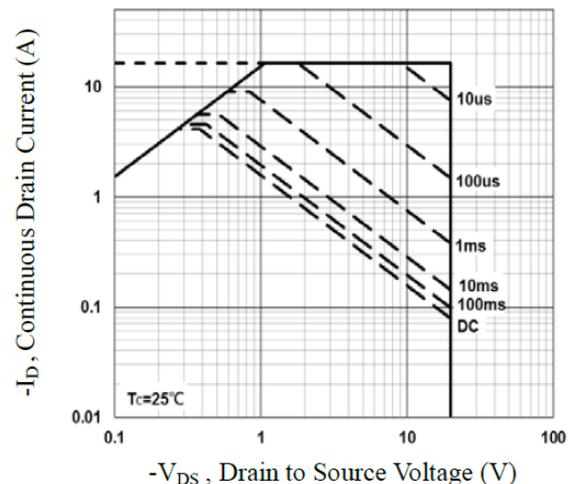


Fig.6 Maximum Safe Operation Area

Typical Characteristics

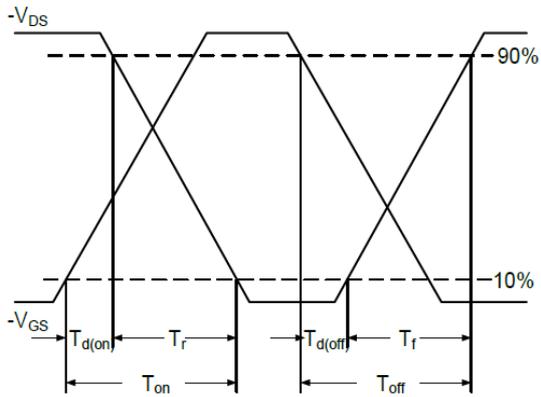


Fig.7 Switching Time Waveform

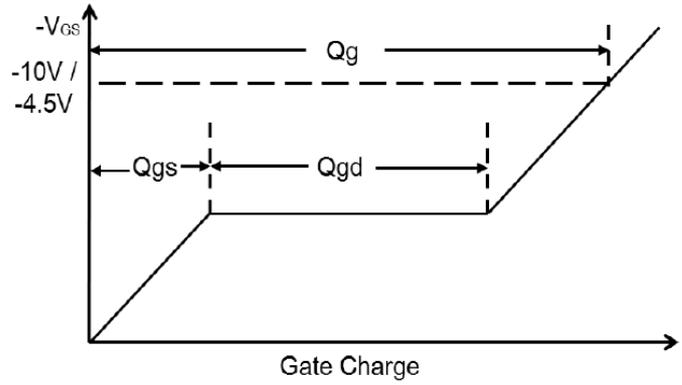
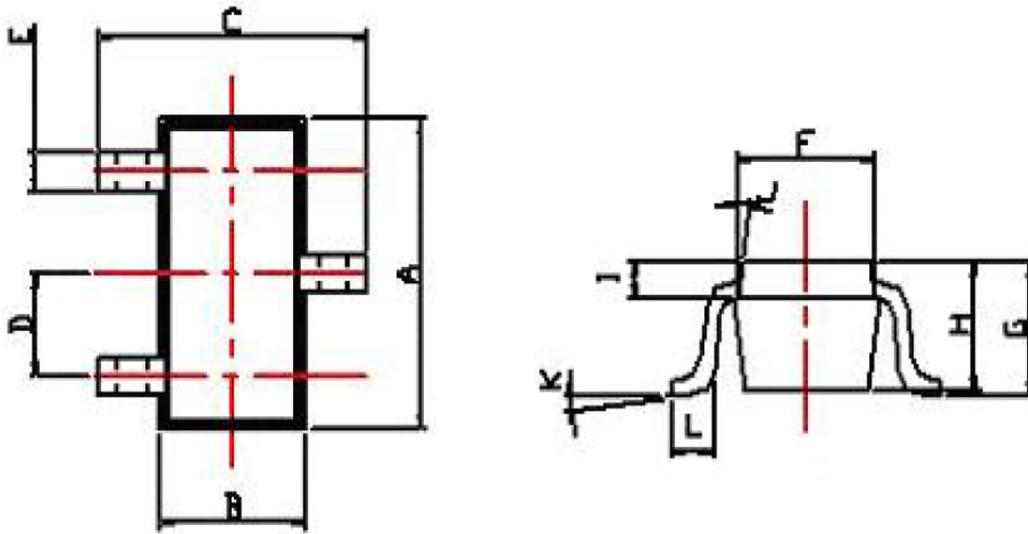


Fig.8 Gate Charge Waveform

Physical Dimensions

3-Pin surface Mount SOT-23-3



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.70	3.10	G	0.9	1.4
B	1.20	1.66	H	0.8	1.30
C	2.37	2.90	I	0.25	0.7
D	0.85	1.15	J	7 ± 2°.	
E	0.350 + 0.15/-0.05		K	0 ~ 10°.	
F	1.07	1.53	L	0.2 (MIN)	